



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





ESDA6V1BC6

ASD™

QUAD BIDIRECTIONAL TRANSIL™ SUPPRESSOR FOR ESD PROTECTION

MAIN APPLICATIONS

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Video equipment

This device is particularly adapted to the protection of symmetrical signals

FEATURES

- 4 Bidirectional Transil functions
- ESD Protection for data, Signal and V_{CC} Bus
- Stand off voltage range: ± 5 V
- Low leakage current $< 1\mu\text{A}$
- Peak pulse power (8/20 μs); 80W

DESCRIPTION

The ESDA6V1BC6 is a monolithic array designed to protect up to 4 lines in a bidirectional way against ESD transients.

The device is ideal for situations where board space is at a premium.

BENEFITS

- High ESD protection level: up to 25kV
- High integration
- Suitable for high density boards

COMPLIES WITH THE FOLLOWING STANDARDS:

- IEC61000-4-2 level 4:
 - 15kV (air discharge)
 - 8kV (contact discharge)
- MIL STD 883E-Method 3015-6: class3 (Human Body Model)

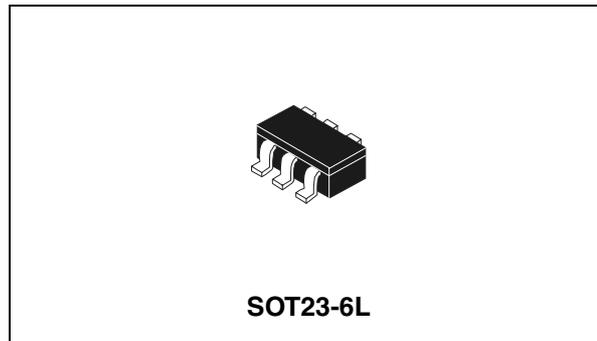
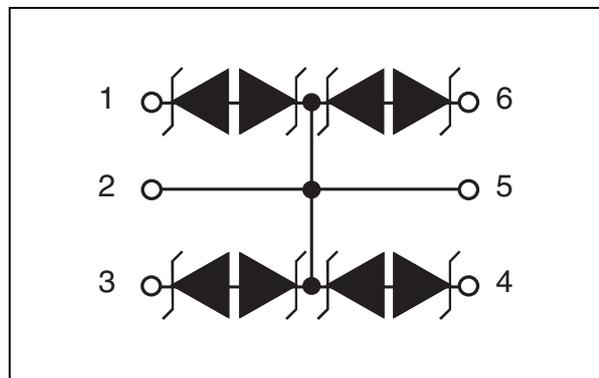


Table 1: Order Code

Part Number	Marking
ESDA6V1BC6	BS55

Figure 1: Functional Diagram



TM: ASD is a trademark of STMicroelectronics.

ESDA6V1BC6

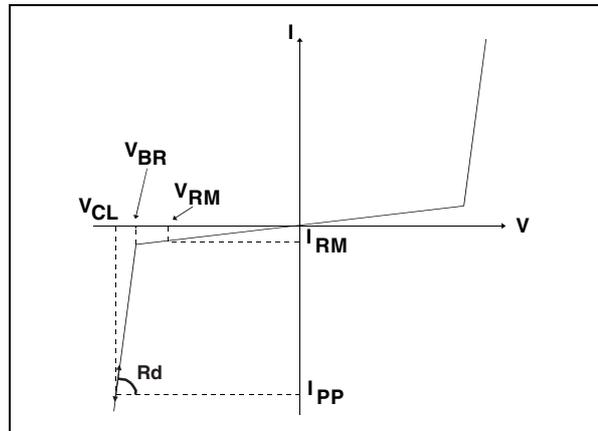
Table 2: Absolute Maximum Ratings ($T_{amb} = 25^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
V_{PP}	ESD discharge	MIL STD 883C - Method 3015-6	25
		IEC61000-4-2 air discharge	15
		IEC61000-4-2 contact discharge	8
P_{PP}	Peak pulse power (8/20 μs)	80	W
T_j	Junction temperature	150	$^{\circ}\text{C}$
T_{stg}	Storage temperature range	-55 to +150	$^{\circ}\text{C}$
T_L	Maximum lead temperature for soldering during 10 s at 5mm for case	260	$^{\circ}\text{C}$
T_{op}	Operating temperature range (note 1)	-40 to +125	$^{\circ}\text{C}$

Note 1: Variation of parameters is given by curves.

Table 3: Electrical Characteristics ($T_{amb} = 25^{\circ}\text{C}$)

Symbol	Parameter
V_{RM}	Stand-off voltage
V_{BR}	Breakdown voltage
V_{CL}	Clamping voltage
I_{RM}	Leakage current
I_{PP}	Peak pulse current
αT	Voltage temperature coefficient
V_F	Forward voltage drop
C	Capacitance
R_d	Dynamic resistance



Type	V_{BR} @		I_R	I_{RM} @ V_{RM}		R_d typ. note 2	αT max.	C typ. 0V bias
	min.	max.		max.				
	V	V		μA	V			
ESDA6V1BC6	6.1	8	1	1	5	1.35	$3 \times 10^{-4}/^{\circ}\text{C}$	20

Note 2: Square pulse, $I_{PP} = 3\text{A}$, $t_p = 2.5\mu\text{s}$.

Figure 2: Relative variation of peak pulse power versus initial junction temperature

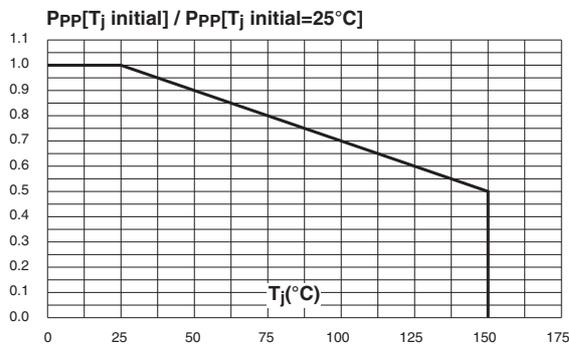


Figure 3: Peak pulse power versus exponential pulse duration

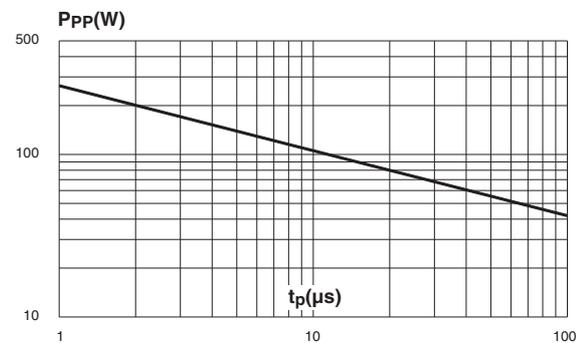


Figure 4: Clamping voltage versus peak pulse current (typical values, rectangular waveform)

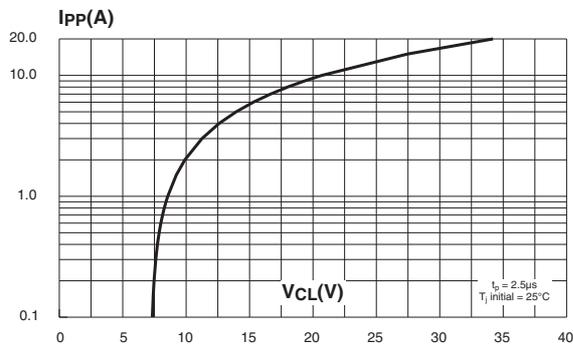


Figure 5: Junction capacitance versus line voltage applied (typical values)

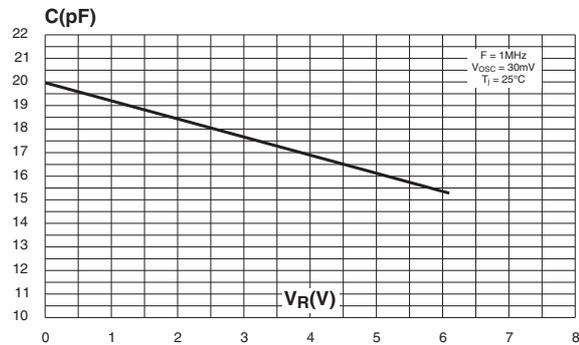
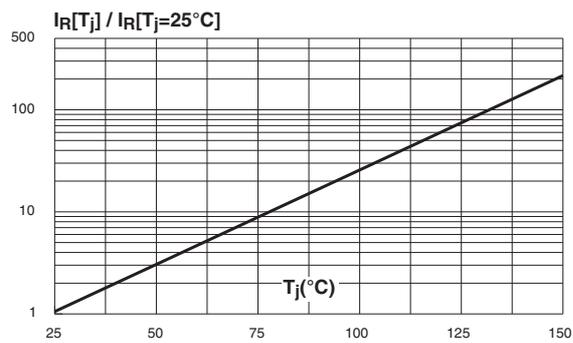


Figure 6: Relative variation of leakage current versus junction temperature (typical values)



1. ESD protection by ESDA6V1-4BC6

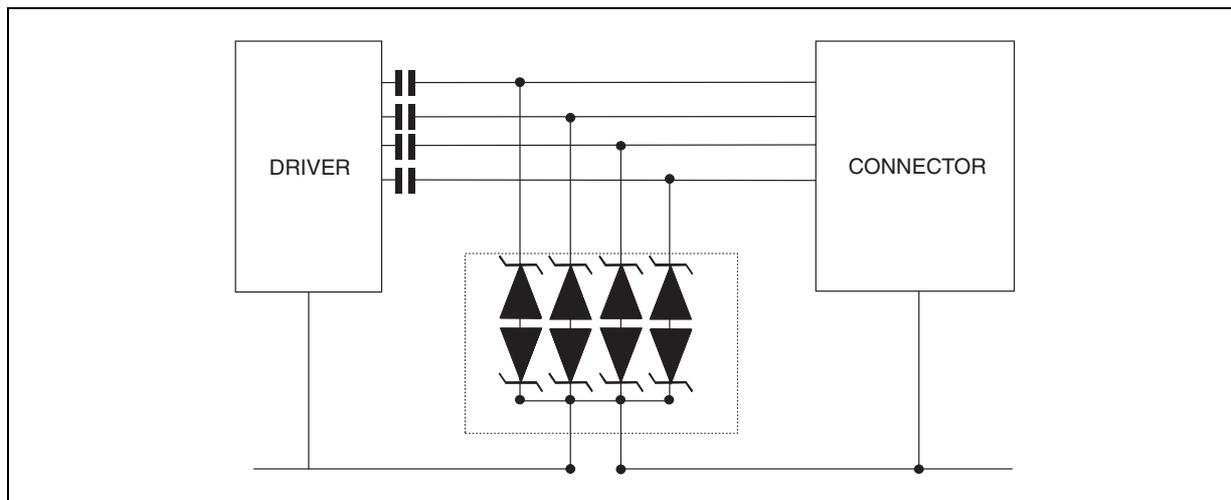
With the focus of lowering the operation levels, the problem of malfunction caused by the environment is critical. Electrostatic discharge (ESD) is a major cause of failure in electronic system.

Transient Voltage Suppressors are an ideal choice for ESD protection and have proven capable in suppressing ESD events. They are capable of clamping the incoming transient to a low enough level such that damage to the protected semiconductor is prevented.

Surface mount TVS arrays offer the best choice for minimal lead inductance.

They serve as parallel protection elements, connected between the signal line to ground. As the transient rises above the operating voltage of the device, the TVS array becomes a low impedance path diverting the transient current to ground.

Figure 7: Bidirectional protection for 0V biased signals



The ESDA6V1BC6 array is the ideal product for use as board level protection of ESD sensitive semiconductor components.

The tiny SOT23-6L package allows design flexibility in the design of “crowded” boards where the space saving is at a premium. This enables to shorten the routing and can contribute to improve ESD performance.

2. Circuit Board Layout

Circuit board layout is a critical design step in the suppression of ESD induced transients. The following guidelines are recommended :

- The ESDA6V1BC6 should be placed as near as possible to the input terminals or connectors.
- Minimise the path length between the ESD suppressor and the protected device
- Minimise all conductive loops, including power and ground loops
- The ESD transient return path to ground should be kept as short as possible.
- Use ground planes whenever possible.

Figure 8: Ordering information scheme

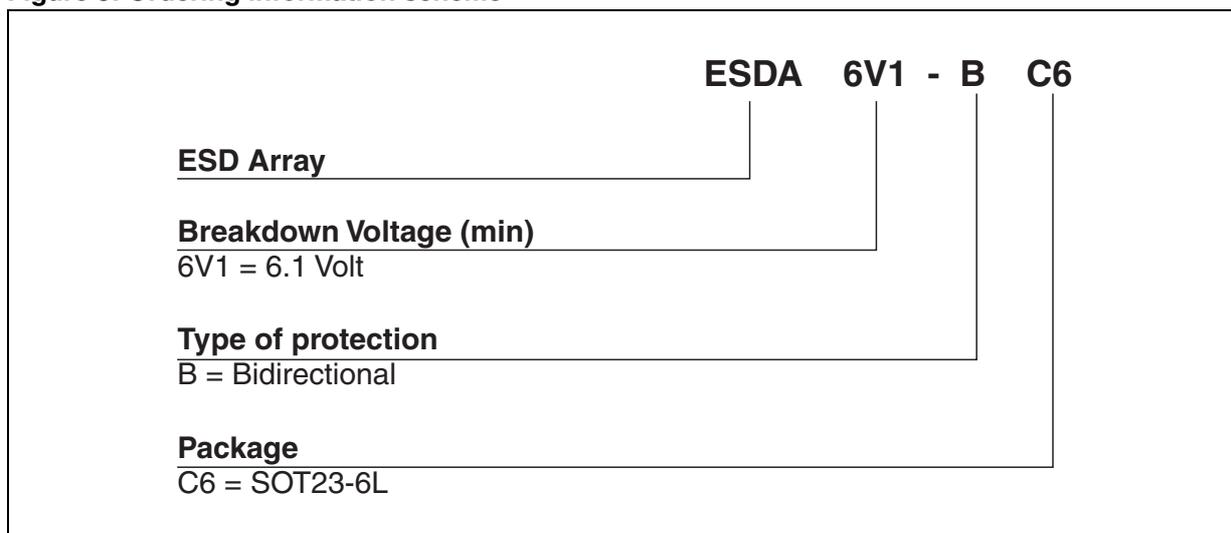


Figure 9: SOT23-6L Package Mechanical Data

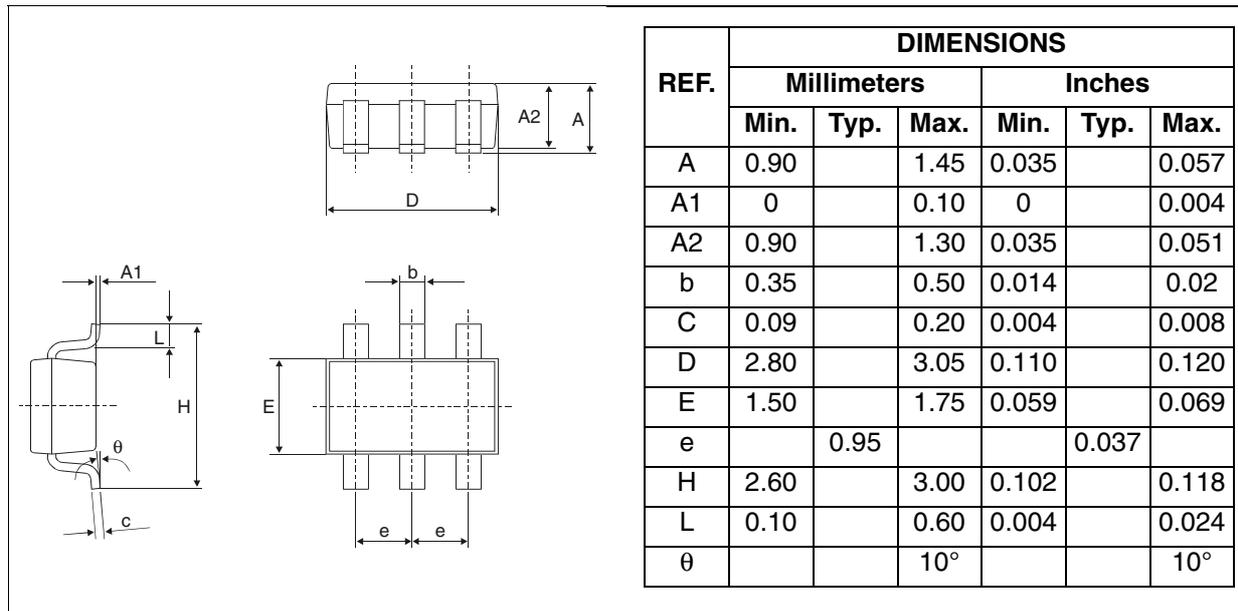


Figure 10: Foot Print Dimensions (in millimeters)

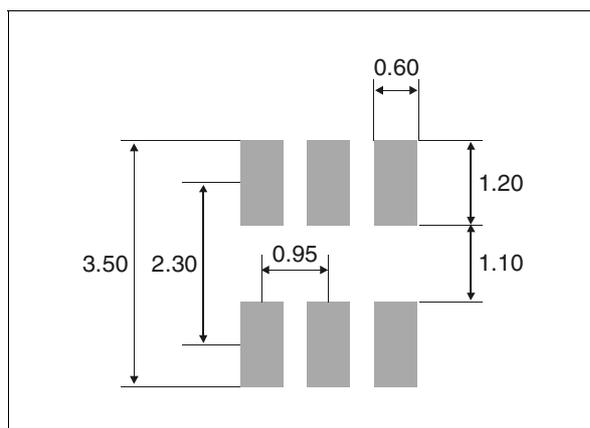


Table 4: Ordering Information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
ESDA6V1BC6	BS55	SOT23-6L	16.7 mg	3000	Tape & reel

Table 5: Revision History

Date	Revision	Description of Changes
Jan-2002	1A	First issue.
4-Nov-2004	2	SOT23-6L package dimensions change for reference “D” from 3.0 millimeters (0.118 inches) to 3.05 millimeters (0.120 inches).

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics.
All other names are the property of their respective owners

© 2004 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America
www.st.com